PCN Number:	20170308002	**PCN Date:**	Mar 9 2017
Title:	Qualification of an additional Assembly and Material Set for Select Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Sept 9 2017	**Estimated Sample Availability:**	Provided upon Request

Change Type:

☒	Assembly Site	☐	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of TI Taiwan as an additional Assembly site for the devices listed below. Construction differences are as follows:

What	Carsem	TI Taiwan
Mount Compound	SID#434165	**4147858**
Mold Compound	SID#438360	**4211880**
Leadframe finish	NiPdAu	**NiPdAu (Roughened)**

Reason for Change:

Continuity of Supply

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
Carsem	CAR	MYS	Ipoh
TI Taiwan	**TAI**	**TWN**	**Chung Ho, New Taipei City**

Sample product shipping label (not actual product label)

Topside Device marking (if included):
Assembly site code for CAR= V
Assembly site code for TITL = T

Product Affected	
UC2625MDWREP	V62/08624-01YE

TEXAS INSTRUMENTS

TI Information
Selective Disclosure

Qualification Report

UC2625MDWREP Roughened leadframe Qual - TAI
Approve Date 23-Sep-2016

Product Attributes

Attributes	Qual Device: UC2625MDWREP	QBS Process: UC2526ADW	QBS Process: UA78M33QDCYRQ1	QBS Process: UA78M05QDCYRQ1	QBS Package Reference: MSP430F123IDWR	QBS Package Reference: SN65LBC170DW	QBS Package Reference: SN65LBC170DW	QBS Package Reference: ULQ2003AQDRQ1
Assembly Site	TAI	CRS	HNT	HNT	TAI	MLA	MLA	FMX
Package Family	SOIC (WIDE)	SOIC (WIDE)	SOT	SOT	SOIC	SOIC	SOIC	SOIC
Flammability Rating	-	-	-	-	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	SHE	SFAB	SFAB	TSMC	DFAB	DFAB	SFAB
Wafer Process	JI-PWR2	Bip-SLM	JI Linear	JI Linear	0.35UM-TSMC	LBC3S	LBC3S	JI1-SLM

- QBS: Qual By Similarity
- Qual Device UC2625MDWREP is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: UC2625MDWREP	QBS Process: UC2526ADW	QBS Process: UA78M33QDCYRQ1	QBS Process: UA78M05QDCYRQ1	QBS Package Reference: MSP430F123IDWR	QBS Package Reference: SN65LBC170DW	QBS Package Reference: SN65LBC170DW	QBS Package Reference: ULQ2003AQDRQ1
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	2/800/0	3/1600/0				
HTOL	Life Test, 125C	1000 Hours	-	3/347/0	1/77/0	3/231/0				
AC	Autoclave 121C	96 Hours	-	3/231/0			1/77/0	1/77/0	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0				-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass				-	Pass	Pass	-
HAST	Biased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0	1/77/0	3/231//0	-	-	-	3/231/0
HAST	Biased HAST, 130C/85%RH	240 Hours	1/77/0			-	-	-	-	-
HTOL	Life Test, 150C	408 Hours	-				-	-	-	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/135/0			-	-	-	1/45/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-				1/77/0	1/77/0	3/231/0	-
SD	Solderability	Pb Free	-				-	-	-	1/15/0
SD	Surface Mount Solderability	Pb	1/22/0				-	-	-	1/15/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0			1/77/0	1/77/0	3/231/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

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USA	PCNAmericasContact@list.ti.com
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